MOSFET – N-Channel, Small Signal, SOT-23

60 V, 115 mA

2N7002L, 2V7002L

ON Semiconductor®

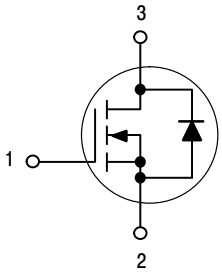
www.onsemi.com

$V_{(BR)DSS}$	$R_{DS(on)}$ MAX	I_D MAX
60 V	7.5 Ω @ 10 V, 500 mA	115 mA

Features

- 2V Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q101 Qualified and PPAP Capable (2V7002L)
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

N−Channel



MAXIMUM RATINGS

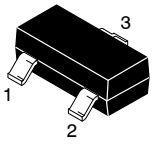
Rating	Symbol	Value	Unit
Drain−Source Voltage	V_{DSS}	60	Vdc
Drain−Gate Voltage (R_{GS} = 1.0 MΩ)	V_{DGR}	60	Vdc
Drain Current – Continuous T_C = 25°C (Note 1) T_C = 100°C (Note 1) – Pulsed (Note 2)	I_D I_D I_{DM}	±115 ±75 ±800	mAdc
Gate−Source Voltage – Continuous – Non−repetitive ($t_p \le 50$ μs)	V_{GS} V_{GSM}	±20 ±40	Vdc Vpk

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR−5 Board (Note 3) T_A = 25°C Derate above 25°C Thermal Resistance, Junction−to−Ambient	P_D $R_{\theta JA}$	 225 1.8 556	 mW mW/°C °C/W
Total Device Dissipation (Note 4) Alumina Substrate, T_A = 25°C Derate above 25°C Thermal Resistance, Junction−to−Ambient	P_D $R_{\theta JA}$	 300 2.4 417	 mW mW/°C °C/W
Junction and Storage Temperature	T_J, T_{stg}	−55 to +150	°C

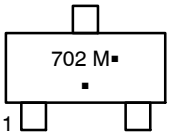
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. The Power Dissipation of the package may result in a lower continuous drain current.
2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.
3. FR−5 = 1.0 x 0.75 x 0.062 in.
4. Alumina = 0.4 x 0.3 x 0.025 in 99.5% alumina.



SOT−23
CASE 318
STYLE 21

MARKING DIAGRAM



702 = Device Code
M = Date Code*
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping†
2N7002LT1G	SOT−23 (Pb−Free)	3,000 Tape & Reel
2N7002LT3G		10,000 Tape & Reel
2N7002LT7G		3,500 Tape & Reel
2V7002LT1G	SOT−23 (Pb−Free)	3,000 Tape & Reel
2V7002LT3G		10,000 Tape & Reel
2N7002LT1H*		3,000 Tape & Reel
2N7002LT7H*		3,500 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*Not for new design.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain−Source Breakdown Voltage (V_{GS} = 0, I_D = 10 μAdc)		$V_{(BR)DSS}$	60	–	–	Vdc
Zero Gate Voltage Drain Current (V_{GS} = 0, V_{DS} = 60 Vdc)	T_J = 25°C T_J = 125°C	I_{DSS}	– –	– –	1.0 500	μAdc
Gate−Body Leakage Current, Forward (V_{GS} = 20 Vdc)		I_{GSSF}	–	–	100	nAdc
Gate−Body Leakage Current, Reverse (V_{GS} = −20 Vdc)		I_{GSSR}	–	–	−100	nAdc
ON CHARACTERISTICS (Note 5)						
Gate Threshold Voltage (V_{DS} = V_{GS}, I_D = 250 μAdc)		$V_{GS(th)}$	1.0	–	2.5	Vdc
On−State Drain Current (V_{DS} ≥ 2.0 $V_{DS(on)}$, V_{GS} = 10 Vdc)		$I_{D(on)}$	500	–	–	mA
Static Drain−Source On−State Voltage (V_{GS} = 10 Vdc, I_D = 500 mAdc) (V_{GS} = 5.0 Vdc, I_D = 50 mAdc)		$V_{DS(on)}$	 – –	 – –	 3.75 0.375	Vdc
Static Drain−Source On−State Resistance (V_{GS} = 10 V, I_D = 500 mAdc) (V_{GS} = 5.0 Vdc, I_D = 50 mAdc)	 T_C = 25°C T_C = 125°C T_C = 25°C T_C = 125°C	$r_{DS(on)}$	 – – – –	 – – – –	 7.5 13.5 7.5 13.5	Ohms
Forward Transconductance (V_{DS} ≥ 2.0 $V_{DS(on)}$, I_D = 200 mAdc)		g_{FS}	80	–	–	mS
DYNAMIC CHARACTERISTICS						
Input Capacitance (V_{DS} = 25 Vdc, V_{GS} = 0, f = 1.0 MHz)		C_{iss}	–	–	50	pF
Output Capacitance (V_{DS} = 25 Vdc, V_{GS} = 0, f = 1.0 MHz)		C_{oss}	–	–	25	pF
Reverse Transfer Capacitance (V_{DS} = 25 Vdc, V_{GS} = 0, f = 1.0 MHz)		C_{rss}	–	–	5.0	pF
SWITCHING CHARACTERISTICS (Note 5)						
Turn−On Delay Time	(V_{DD} = 25 Vdc, I_D ≅ 500 mAdc, R_G = 25 Ω, R_L = 50 Ω, V_{gen} = 10 V)	$t_{d(on)}$	–	–	20	ns
Turn−Off Delay Time		$t_{d(off)}$	–	–	40	ns
BODY−DRAIN DIODE RATINGS						
Diode Forward On−Voltage (I_S = 115 mAdc, V_{GS} = 0 V)		V_{SD}	–	–	−1.5	Vdc
Source Current Continuous (Body Diode)		I_S	–	–	−115	mAdc
Source Current Pulsed		I_{SM}	–	–	−800	mAdc

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

5. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

TYPICAL ELECTRICAL CHARACTERISTICS

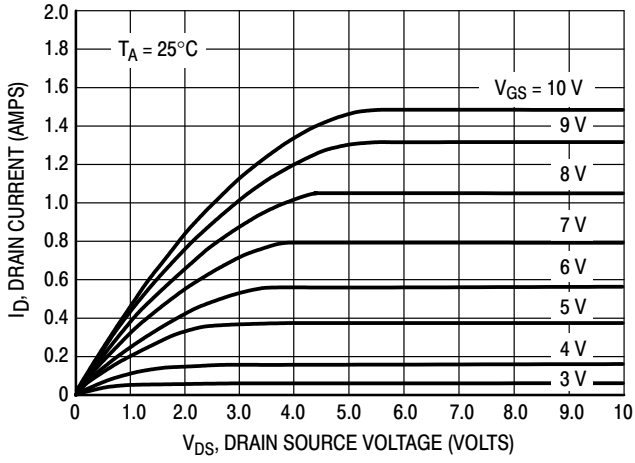


Figure 1. Ohmic Region

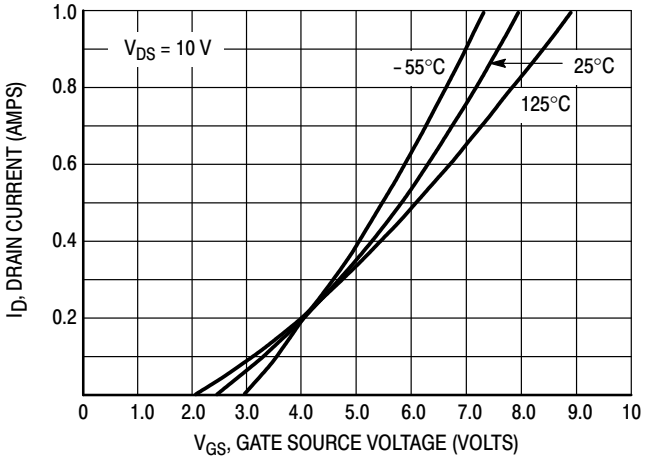


Figure 2. Transfer Characteristics

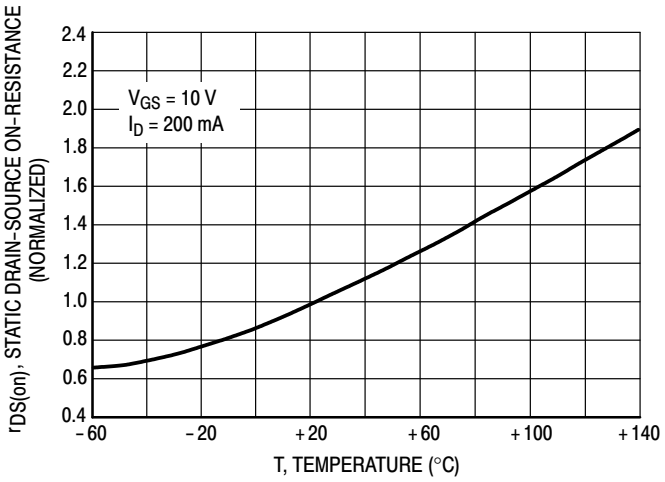


Figure 3. Temperature versus Static Drain−Source On−Resistance

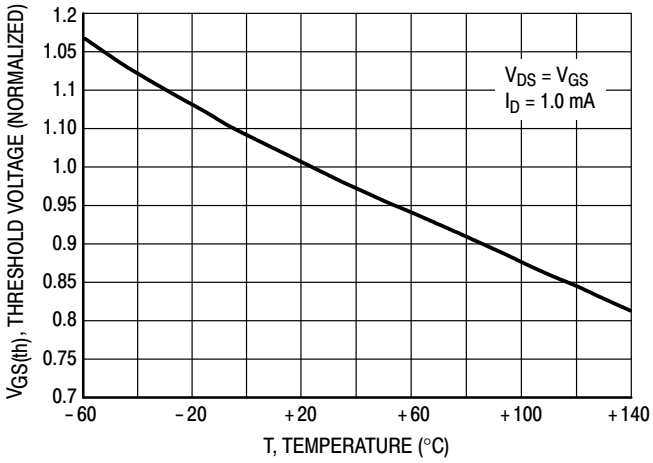


Figure 4. Temperature versus Gate Threshold Voltage

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

SOT−23 (TO−236)
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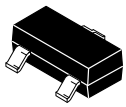
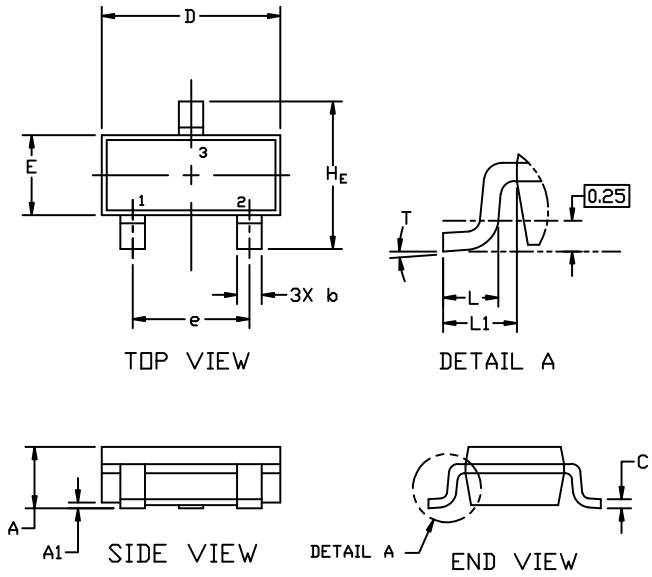
DATE 01 MAR 2023



SCALE 4:1

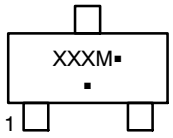


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

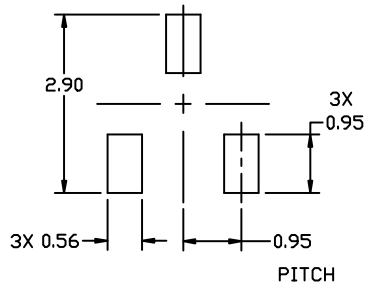
	MILLIMETERS			INCHES		
DIM	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
c	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
H_E	2.10	2.40	2.64	0.083	0.094	0.104
T	0°	---	10°	0°	---	10°

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
M = Date Code
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

DOCUMENT NUMBER:	**98ASB42226B**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.	
DESCRIPTION:	**SOT−23 (TO−236)**		**PAGE 1 OF 2**

SOT−23 (TO−236)
CASE 318
ISSUE AT

DATE 01 MAR 2023

STYLE 1 THRU 5:
CANCELLED

STYLE 6:
PIN 1. BASE
2. EMITTER
3. COLLECTOR

STYLE 7:
PIN 1. EMITTER
2. BASE
3. COLLECTOR

STYLE 8:
PIN 1. ANODE
2. NO CONNECTION
3. CATHODE

STYLE 9:
PIN 1. ANODE
2. ANODE
3. CATHODE

STYLE 10:
PIN 1. DRAIN
2. SOURCE
3. GATE

STYLE 11:
PIN 1. ANODE
2. CATHODE
3. CATHODE−ANODE

STYLE 12:
PIN 1. CATHODE
2. CATHODE
3. ANODE

STYLE 13:
PIN 1. SOURCE
2. DRAIN
3. GATE

STYLE 14:
PIN 1. CATHODE
2. GATE
3. ANODE

STYLE 15:
PIN 1. GATE
2. CATHODE
3. ANODE

STYLE 16:
PIN 1. ANODE
2. CATHODE
3. CATHODE

STYLE 17:
PIN 1. NO CONNECTION
2. ANODE
3. CATHODE

STYLE 18:
PIN 1. NO CONNECTION
2. CATHODE
3. ANODE

STYLE 19:
PIN 1. CATHODE
2. ANODE
3. CATHODE−ANODE

STYLE 20:
PIN 1. CATHODE
2. ANODE
3. GATE

STYLE 21:
PIN 1. GATE
2. SOURCE
3. DRAIN

STYLE 22:
PIN 1. RETURN
2. OUTPUT
3. INPUT

STYLE 23:
PIN 1. ANODE
2. ANODE
3. CATHODE

STYLE 24:
PIN 1. GATE
2. DRAIN
3. SOURCE

STYLE 25:
PIN 1. ANODE
2. CATHODE
3. GATE

STYLE 26:
PIN 1. CATHODE
2. ANODE
3. NO CONNECTION

STYLE 27:
PIN 1. CATHODE
2. CATHODE
3. CATHODE

STYLE 28:
PIN 1. ANODE
2. ANODE
3. ANODE

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